



**N - CHANNEL ENHANCEMENT MODE
LOW THRESHOLD POWER MOS TRANSISTOR**

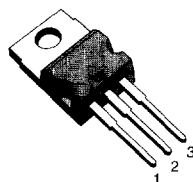
TENTATIVE DATA

TYPE	V _{DSS}	R _{DS(on)}	I _D
STP8N10L	100 V	0.45 Ω	8 A

- AVALANCHE RUGGEDNESS TECHNOLOGY
- 100% AVALANCHE TESTED
- REPETITIVE AVALANCHE DATA AT 100°C
- LOW GATE CHARGE
- HIGH CURRENT CAPABILITY
- LOGIC LEVEL COMPATIBLE INPUT
- 175°C OPERATING TEMPERATURE
- APPLICATION ORIENTED CHARACTERIZATION

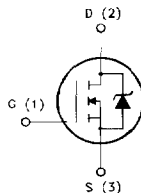
APPLICATIONS

- HIGH CURRENT, HIGH SPEED SWITCHING
- SOLENOID AND RELAY DRIVERS
- REGULATORS
- DC-DC & DC-AC CONVERTERS
- MOTOR CONTROL, AUDIO AMPLIFIERS
- AUTOMOTIVE ENVIRONMENT (INJECTION, ABS, AIR-BAG, LAMPDRIVERS, Etc.)



TO-220

INTERNAL SCHEMATIC DIAGRAM



ABSOLUTE MAXIMUM RATINGS

Symbol	Parameter	Value	Unit
V _{DS}	Drain-source Voltage (V _{GS} = 0)	100	V
V _{DGR}	Drain- gate Voltage (R _{GS} = 20 k Ω)	100	V
V _{GS}	Gate-source Voltage	± 15	V
I _D	Drain Current (continuous) at T _c = 50 °C	8	A
I _D	Drain Current (continuous) at T _c = 100 °C	6	A
I _{DM} (*)	Drain Current (pulsed)	32	A
P _{tot}	Total Dissipation at T _c = 25 °C	65	W
	Derating Factor	0.52	W/°C
T _{stg}	Storage Temperature	-65 to 175	°C
T _j	Max. Operating Junction Temperature	175	°C

(*) Pulse width limited by safe operating area

THERMAL DATA

$R_{\text{th(jc)}}$	Thermal Resistance Junction-case	Max	2.27	°C/W
$R_{\text{th(ja)}}$	Thermal Resistance Junction-ambient	Max	62.5	°C/W
$R_{\text{th(la)}}$	Thermal Resistance Case-sink	Typ	0.5	°C/W
T	Maximum Lead Temperature For Soldering Purpose		300	°C

AVALANCHE CHARACTERISTICS

Symbol	Parameter	Max Value	Unit
I_{AR}	Avalanche Current, Repetitive or Not-Repetitive (pulse width limited by T_J max, $\delta < 1\%$)	8	A
E_{AS}	Single Pulse Avalanche Energy (starting $T_J = 25\text{ °C}$, $I_D = I_{\text{AR}}$, $V_{\text{DD}} = 25\text{ V}$)	32	mJ
E_{AR}	Repetitive Avalanche Energy (pulse width limited by T_J max, $\delta < 1\%$)	8	mJ
I_{AR}	Avalanche Current, Repetitive or Not-Repetitive ($T_c = 100\text{ °C}$, pulse width limited by T_J max, $\delta < 1\%$)	5	A

ELECTRICAL CHARACTERISTICS ($T_{\text{case}} = 25\text{ °C}$ unless otherwise specified)

OFF

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$V_{(\text{BR})\text{DSS}}$	Drain-source Breakdown Voltage	$I_D = 250\text{ }\mu\text{A}$ $V_{\text{GS}} = 0$	100			V
I_{DSS}	Zero Gate Voltage Drain Current ($V_{\text{GS}} = 0$)	$V_{\text{DS}} = \text{Max Rating}$ $V_{\text{DS}} = \text{Max Rating} \times 0.8$ $T_c = 125\text{ °C}$			250 1000	μA μA
I_{GSS}	Gate-body Leakage Current ($V_{\text{DS}} = 0$)	$V_{\text{GS}} = \pm 15\text{ V}$			± 100	nA

ON (*)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$V_{\text{GS(th)}}$	Gate Threshold Voltage	$V_{\text{DS}} = V_{\text{GS}}$ $I_D = 250\text{ }\mu\text{A}$	1		2.5	V
$R_{\text{DS(on)}}$	Static Drain-source On Resistance	$V_{\text{GS}} = 5\text{ V}$ $I_D = 4\text{ A}$ $V_{\text{GS}} = 5\text{ V}$ $I_D = 4\text{ A}$ $T_c = 100\text{ °C}$			0.45 0.90	Ω Ω
$I_{\text{D(on)}}$	On State Drain Current	$V_{\text{DS}} > I_{\text{D(on)}} \times R_{\text{DS(on)max}}$ $V_{\text{GS}} = 5\text{ V}$	8			A

DYNAMIC

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$g_{\text{fs}} (*)$	Forward Transconductance	$V_{\text{DS}} > I_{\text{D(on)}} \times R_{\text{DS(on)max}}$ $I_D = 4\text{ A}$		4		S
C_{iss} C_{oss} C_{rss}	Input Capacitance Output Capacitance Reverse Transfer Capacitance	$V_{\text{DS}} = 25\text{ V}$ $f = 1\text{ MHz}$ $V_{\text{GS}} = 0$		400 120 50		pF pF pF

ELECTRICAL CHARACTERISTICS (continued)**SWITCHING ON**

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$t_{d(on)}$	Turn-on Time	$V_{DD} = 50\text{ V}$ $I_D = 4\text{ A}$		20		ns
t_r	Rise Time	$R_G = 50\ \Omega$ $V_{GS} = 5\text{ V}$ (see test circuit, figure 3)		40		ns
$(di/dt)_{on}$	Turn-on Current Slope	$V_{DD} = 80\text{ V}$ $I_D = 8\text{ A}$ $R_G = 50\ \Omega$ $V_{GS} = 5\text{ V}$ (see test circuit, figure 5)		200		A/ μ s
Q_g	Total Gate Charge	$V_{DD} = 80\text{ V}$ $I_D = 8\text{ A}$ $V_{GS} = 5\text{ V}$		10		nC

SWITCHING OFF

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$t_{r(V_{off})}$	Off-voltage Rise Time	$V_{DD} = 80\text{ V}$ $I_D = 8\text{ A}$		50		ns
t_f	Fall Time	$R_G = 50\ \Omega$ $V_{GS} = 5\text{ V}$		50		ns
t_c	Cross-over Time	(see test circuit, figure 5)		100		ns

SOURCE DRAIN DIODE

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
I_{SD}	Source-drain Current				8	A
$I_{SDM}^{(*)}$	Source-drain Current (pulsed)				32	A
$V_{SD}^{(*)}$	Forward On Voltage	$I_{SD} = 8\text{ A}$ $V_{GS} = 0$			1.5	V
t_{rr}	Reverse Recovery Time	$I_{SD} = 8\text{ A}$ $di/dt = 100\text{ A}/\mu\text{s}$ $V_{DD} = 30\text{ V}$ $T_J = 150\text{ }^\circ\text{C}$		80		ns
Q_{rr}	Reverse Recovery Charge	(see test circuit, figure 5)		0.15		μC
I_{RRM}	Reverse Recovery Current			4		A

(*) Pulsed: Pulse duration = 300 μ s, duty cycle 1.5 %

(*) Pulse width limited by safe operating area